

IN THE CLAIMS:

Please amend claims 1 and 2 as follows.

1. (Currently Amended) A semiconductor integrated circuit device comprising:

a semiconductor substrate defining a plurality of rows, each row including areas for a sequence of cells;

a plurality of active regions disposed in each of said rows constituting semiconductor elements of associated cells;

at least one wiring region of a stripe shape elongated along a direction of a row, defined on said semiconductor substrate outside of said active regions in each row, and including wirings belonging to the associated cells, each wiring region having height, so that the wiring region in a same row has a varying height from a first location position to a second location position in a direction crossing the row direction, the at least one wiring region having a locally varying height.

2. (Currently Amended) ~~The semiconductor integrated circuit device according to claim 1~~ A semiconductor integrated circuit device comprising:

a semiconductor substrate defining a plurality of rows, each row including areas for a sequence of cells;

a plurality of active regions disposed in each of said rows constituting semiconductor elements of associated cells;

a wiring region of stripe shape elongated along a direction of row, defined on said semiconductor substrate outside of said active regions in each row, and including wirings belonging to the associated cells, each wiring region having height in a direction

crossing the row direction, the wiring region having locally different height, wherein wiring regions of opposing cells in opposing rows have mutually fitting shapes.

3. (Previously Presented) The semiconductor integrated circuit device according to claim 1, wherein the wirings include a connection of different wiring layers.

4-18. (Cancelled)